

SPECIFICATIONS

BGA 604

Mechanical

Contact Retention Force: 0.13Kg /pin min.
Durability: 50 Cycles

BGA Series CPU Socket

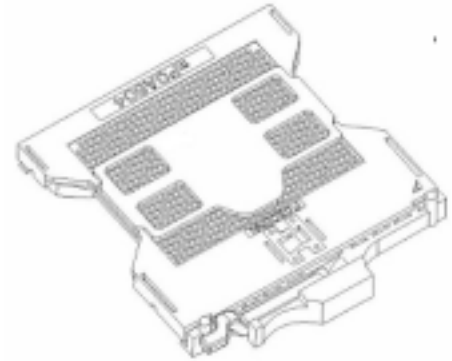
Vertical, SMT Type
1.27X1.27mm [.05X.05"]Pitch
604Pos.

Electrical

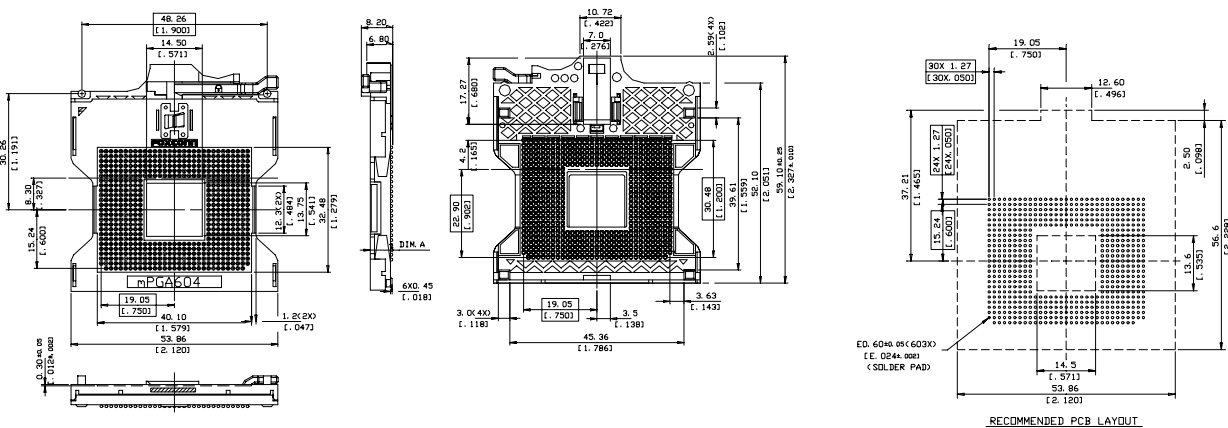
Contact Resistance: 25mΩ max.
Dielectric Withstanding Voltage: 360V VRMS Min
Insulation Resistance: 800MΩ min.

Physical

Cover: Thermoplastic, UL 94V-0 rated, Natural color
Base: Thermoplastic, UL 94V-0 rated, Black color
Cam: Zinc Alloy,
Contact: Copper alloy
Plating: See "ORDERING INFORMATION"
Operating Temperature: -40°C to +105°C



DRAWING



ORDERING INFORMATION

PRODUCT NO.: P Z 6 0 4 0 3 - 01 3 - T

- Actual Loading NO. of Pos. 604=604Pos.
- Solder Ball Type: 0=Sn/Pb Type
- Gold Plating On Contact Area 3=30u" Gold Plating On Contact Area
- Pick-up Design 01=Plastic Cap
- T=Tooless Type
- 3=Dual Arm Contact